

ABSTRACT

A method for creating electrical interconnects between a semiconductor die and package.

In the preferred embodiment, an insulating material is applied over the die and extends to the substrate contact pads, leaving a portion of each contact pad exposed. Holes are then trimmed

5 through the insulating material, exposing at least a portion of each die bond pad. A conductive material is then applied over the die, flowing into the holes, contacting the die bond pads, and extending out to contact at least a portion of each substrate contact pad. In another preferred

embodiment, an electrically conductive bump may be formed on each die bond pad, protruding through said non-conductive material and at least partially through said conductive material. The

10 conductive layer is then laser trimmed, forming conductive patches that serve as electrical interconnects between the die and package substrate.